

WHAT IS CLAIMED IS:

1. A semiconductor device comprising:

a lead frame having a die pad, supporting leads continuously formed with said die pad, and a plurality of leads, first ends of said plurality of leads being disposed to surround said die pad in a plane view;

a semiconductor chip mounted on said die pad, said semiconductor chip having an integrated circuit and bonding pads formed on a main surface thereof, said main surface of said semiconductor chip having a quadrilateral shape, said bonding pads being disposed along four sides of said main surface of said semiconductor chip, said die pad having a size which is smaller than that of said semiconductor chip;

a plurality of bonding wires electrically connecting said bonding pads with the first ends of said plurality of leads respectively; and

a resin body sealing said semiconductor chip, said die, said supporting leads, portions of the plurality of leads and said plurality of bonding wires,

wherein a pitch between first ones of adjacent bonding pads at each of four corners defined by said four sides of said main surface of said semiconductor chip is wider than a pitch between second ones of adjacent bonding pads which are disposed at a relatively central position of each of said four sides as compared to said four corners.

2. A semiconductor device according to claim 1, wherein said semiconductor chip is bonded to said die pad by an adhesive.

3. A semiconductor device according to claim 2, wherein said die pad has a circular shape in said plane view.

4. A semiconductor device according to claim 2, wherein said die pad has a cross shape in said plane view.

5. A semiconductor device according to claim 2, wherein said resin member is formed in a tetragonal shape, and wherein portions of said plurality of leads protrude outwardly from said resin member at four sides of said resin member.

6. A semiconductor device according to claim 2, wherein a part of said resin member contacts with a rear surface of said semiconductor chip except for areas to which said die pad is bonded.